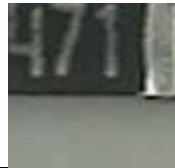


# MATERIAL DECLARATION SHEET

**BOURNS®**

Material Number	CRS 0603-A (> 1Ω)				
Product Line	High power & anti-surge chip resistors				
Compliance Date	04/11/2017				
RoHS Compliant	Yes (with Exemption)	MSL	1		

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)	
1	Ceramic	Substrate	1.811	Aluminum oxide	1344-28-1	96	77.314	80.535	
				Silicon dioxide	14808-60-7	4	3.221		
				Magnesium oxide	1309-48-4				
2	Top conductor	Silver	0.0464	Silver	7440-22-4	100	2.063	2.063	
3	Bottom conductor	Silver	0.0201	Silver	7440-22-4	100	0.894	0.894	
4	Resistor	Ruthenium Oxide	0.0264	Silver	7440-22-4	40	0.469	1.174	
				Ruthenium oxide	12036-10-1	20	0.235		
				Palladium	7440-05-3	15	0.176		
				Glass (no declarables)	65997-18-4	14.9	0.175		
				Lead	7439-92-1	10.1	0.119		

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**BOURNS®**

5	First encapsulating	Glass	0.0252	Silica	14808-60-7	74	0.83	1.121
				Glass (no declarables)	65997-18-4	12	0.134	
				Aluminum oxide	1344-28-1	6	0.067	
				Chromium oxide	1308-38-9	8	0.090	
6	Overcoat	Resin	0.0517	Resin	25036-25-3	100	2.299	2.299
7	Side conductor	Silver	0.1309	Silver	7440-22-4	85	4.948	5.821
				Resin	9003-36-5	15	0.873	
8	Plating (Middle)	Nickel	0.0525	Nickel	7440-02-0	100	2.335	2.335
9	Plating (Outer)	Tin	0.0782	Tin	7440-31-5	100	3.478	3.478
10	Marking	Resin	0.0063	Resin	29690-82-2	70	0.196	0.28
				Titanium oxide	1317-80-2	30	0.084	
		Total weight	2.2487					

This Document was updated on: 04/11/2017

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption: 7( c )-1 Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.